



Surface Mount General Purpose Rectifier

Features

- Low profile package
- Ideal for automated placement
- Glass passivated chip junction
- High forward surge capability
- Meets MSL level 1, per J-STD-020, LF maximum peak of 260 °C

Typical Applications

For use in general purpose rectification of power supplies, inverters, converters, and freewheeling diodes for consumer, and telecommunication.

Mechanical Data

Case: TO-277B

Molding compound meets UL 94 V-0 flammability rating

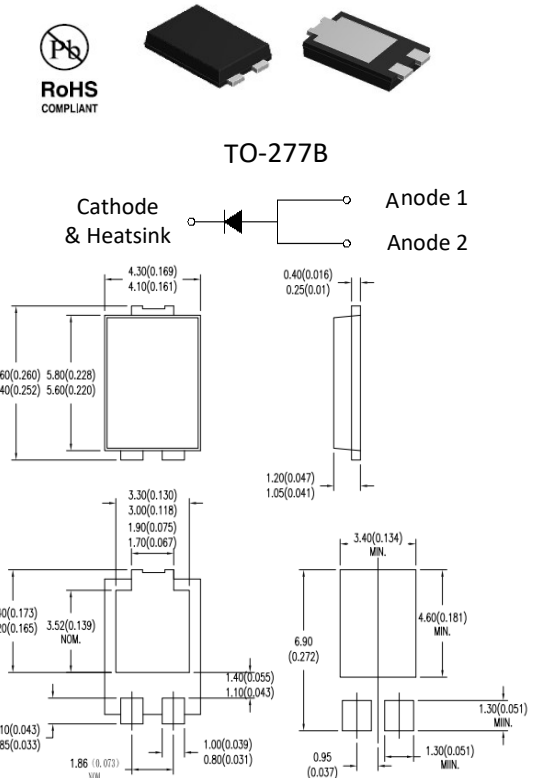
Moisture sensitivity level: level 1, per J-STD-020

Terminal: Matte tin plated leads, solderable per JESD22-B102

Meet JESD 201 class 2 whisker test

Polarity: Indicated by cathode band

Weight: 0.095g (approximately)



Maximum Ratings (Ta=25°C Unless otherwise specified)

PARAMETER	SYMBOL	UNIT	S10A	S10B	S10D	S10G	S10J	S10K	S10M
Maximum Repetitive peak reverse voltage	V_{RRM}	V	50	100	200	400	600	800	1000
Maximum RMS Voltage	V_{RMS}	V	35	70	140	280	420	560	700
Maximum DC Blocking Voltage	V_{DC}	V	50	100	200	400	600	800	1000
Average Rectified Output Current @60Hz sine wave, Resistance load, TL (FIG.1)	I_O	A	10						
Forward Surge Current (Non-repetitive) @60Hz Half-sine wave, 1 cycle, Tj=25°C	I_{FSM}	A	200						
Forward Surge Current (Non-repetitive) @1ms, square wave, 1 cycle, Tj=25°C			400						
Current squared time @1ms≤t≤8.3ms Tj=25°C	I^2t	A ² s	166						
Storage Temperature	Tstg	°C	-55 ~ +150						
Junction Temperature	Tj	°C	-55 ~ +150						

Electrical Characteristics (Ta=25°C Unless otherwise specified)

PARAMETER	SYMBOL	UNIT	TEST CONDITIONS	S10A	S10B	S10D	S10G	S10J	S10K	S10M
Maximum instantaneous forward voltage	V_F	V	$I_{FM}=10A$	1.1						
Maximum DC reverse current at rated DC blocking voltage	I_R	μA	Tj=25°C	5						
			Tj=125°C	100						
Typical junction capacitance	Cj	pF	Measured at 1MHz and Applied Reverse Voltage of 4.0 V.D.C	55						



■ Thermal Characteristics (T_a=25°C Unless otherwise specified)

PARAMETER	SYMBOL	UNIT	S10A	S10B	S10D	S10G	S10J	S10K	S10M
Typical Thermal resistance	R _θ J-A(1)	°C/W	50						
	R _θ J-L(1)		10						
	R _θ J-C(1)		8						

Note(1)

Thermal resistance from junction to ambient and from junction to lead mounted on P.C.B. with 0.6" x 0.6" (16 mm x 16 mm) copper pad areas

■ Characteristics(Typical)

FIG.1: I_o-TL Curve

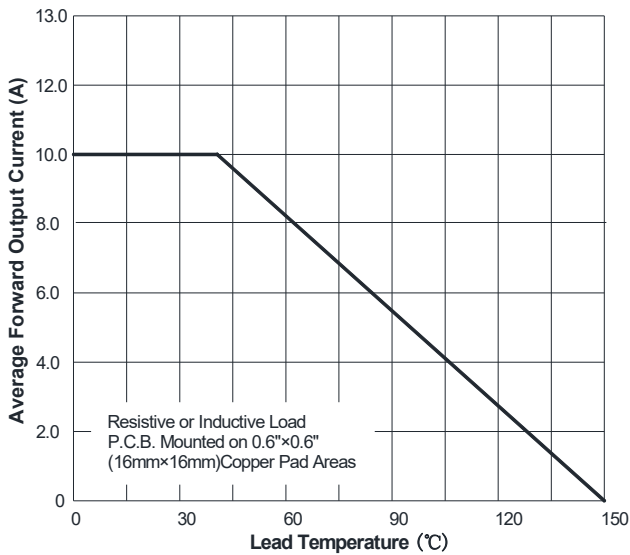


FIG.2: Forward Surge Current Capability

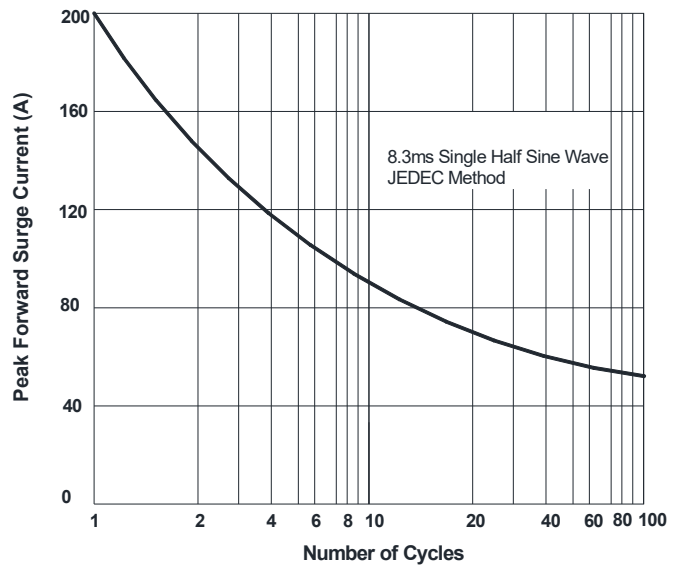


FIG.3: Typical Forward Voltage

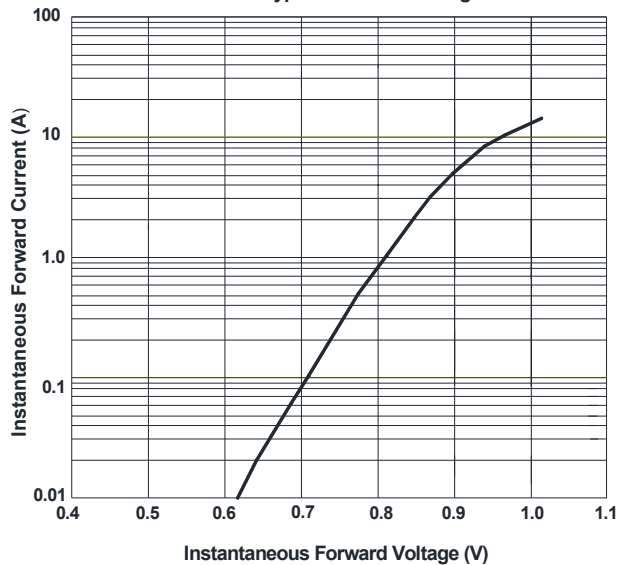


FIG.4: Typical Reverse Characteristics

